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Contents

vii *Conference Committee*

OPTICAL INTERCONNECT SYSTEMS I

- 12007 02 **Paradigm shift in high-speed interface technology (Invited Paper)** [12007-3]
- 12007 03 **An all-optical 8-bit RAM storage unit with 2×4-bit WDM-formatted data words** [12007-4]
- 12007 04 **Optical connection of top-level supercomputers: current status and future expectations (Invited Paper)** [12007-5]

OPTICAL INTERCONNECT SYSTEMS II

- 12007 05 **Bandwidth evaluation of multimode waveguides for optical interconnects application using an optical sampling technique (Invited Paper)** [12007-9]
- 12007 06 **Coherent photonic neuromorphic computing for high-speed deep learning applications (Invited Paper)** [12007-10]
- 12007 07 **LED-array based optical interconnects for chip-to-chip communications with integrated CMOS drivers, detectors, and circuitry (Invited Paper)** [12007-11]

OPTICAL INTERCONNECT DEVICES AND COMPONENTS I

- 12007 08 **Commoditizing the uncommoditized: chip-scale LiDAR (Invited Paper)** [12007-12]

OPTICAL INTERCONNECT DEVICES AND COMPONENTS II

- 12007 09 **Slow-light assisted and wavelength tunable TM waveguide on QCL/QCD compatible platform for mid-infrared lab-on-chip absorption spectroscopy** [12007-19]

NOVEL OPTICAL WAVEGUIDE AND PHOTONIC INTEGRATION TECHNOLOGIES

- 12007 0A **Single-mode polymer waveguide for fan-in/fan-out of multicore fiber by the mosquito method** [12007-23]

- 12007 0B **Laser direct writing of short-range interconnect interfacing structures (Invited Paper)** [12007-24]
- 12007 0C **Fast ethernet operation of a printed optical transmission path using industrial integration technologies** [12007-25]
- 12007 0D **Low-loss optical single-mode waveguide platform in thin glass with wide spectral range** [12007-26]
- 12007 0E **Novel etching process based on molten salts for optical fiber components** [12007-40]
- 12007 0F **Chip-to-chip optical interconnect using direct optical wire bonding** [12007-41]
- 12007 0G **Flexographically printed optical waveguides for complex low-cost optical networks** [12007-43]

HYBRID INTEGRATED OPTICAL LINK MODULES

- 12007 0H **Transceiver circuits for high-baudrate optical interconnects (Invited Paper)** [12007-33]
- 12007 0I **Energy efficient transmitters for high bandwidth density links** [12007-34]
- 12007 0J **Heterogeneous integration of VCSELs on 3 μm SOI silicon photonics platform with up-reflecting mirrors** [12007-35]
- 12007 0K **Assembly of mobile 5G transceiver based on photonic motherboard (Invited Paper)** [12007-36]

HYBRID DEVICE INTEGRATION APPROACHES FOR PIC

- 12007 0L **An uncooled CW-WDM MSA compliant multi-wavelength laser source operating from 15-100°C for WDM CMOS applications (Invited Paper)** [12007-28]
- 12007 0M **Glass-molded optical interposers for wafer scale photonic integrated circuit packaging in 800G modules and co-packaged optics** [12007-29]
- 12007 0N **Silicon nitride C-band grating couplers with reduced waveguide back-reflection** [12007-31]
- 12007 0O **Inverse designed broadband on-chip photonic couplers and polarization-independent wavelength demultiplexing (Invited Paper)** [12007-32]
- 12007 0P **Analytical analysis of the optical parameters of lenses for astigmatic beams** [12007-53]

FIBER OPTICS AND MICRO-OPTICS INTEGRATION

- 12007 OQ **Fiber management for high-density connectivity In co-packaged switches (Invited Paper)**
[12007-44]
- 12007 OR **Advancement in optical interconnect technology for high speed data transmission** [12007-45]
- 12007 OS **High-density passive multi-fiber assembly to single-mode polymer waveguides using embedded v-grooves for co-packaged optics** [12007-48]

POSTER SESSION

- 12007 OT **Design and analysis of all optical reflective code using MIM waveguides in Mach-Zehnder interferometer** [12007-49]
- 12007 OU **On-chip silicon-organic hybrid entangled photon pair source** [12007-51]
- 12007 OV **Optical phased array based on subwavelength grating antennas** [12007-52]

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